

Product Change Notification - JAON-22STDI069

Date: 20 Oct 2017
Product Category: 8-bit PIC Microcontrollers
Notification subject: CCB 2999 Final Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 90K and 120K wafer technologies available in 28L SSOP package.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 90K and 120K wafer technologies available in 28L SSOP package.

Pre Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire.

Post Change:

Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

| | Pre Change | Post Change | |
|----------------------------------|---|---|--|
| Assembly Site | Microchip Technology Thailand - HQ (MTAI) | Microchip Technology Thailand - HQ (MTAI) | Microchip Technology Thailand - Branch (MMT) |
| Wire material | PdCu Wire | PdCu Wire | CuPdAu Wire |
| Die attach material | 3280 | 3280 | 3280 |
| Molding compound material | G600 | G600 | G600 |
| Lead frame material | CDA194 | CDA194 | CDA194 |

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:
November 24, 2017 (date code: 1747)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

| | July 2017 | | | | --> | October 2017 | | | | November 2017 | | | |
|-------------------------------|-----------|----|----|----|-----|--------------|----|----|----|---------------|----|----|----|
| | 27 | 28 | 29 | 30 | | 40 | 41 | 42 | 43 | 44 | 45 | 46 | 47 |
| Initial PCN Issue Date | X | | | | | | | | | | | | |
| Qual Report Availability | | | | | | | X | | | | | | |
| Final PCN Issue Date | | | | | | | X | | | | | | |
| Estimated Implementation Date | | | | | | | | | | | | | X |

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
July 6, 2017: Issued initial notification.
October 20, 2017: Issued final notification. Provided estimated first ship date to be on November 24, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-22STDI069_Qual_Report.pdf](#)
 - [PCN_JAON-22STDI069_Affected_CPN.pdf](#)
 - [PCN_JAON-22STDI069_Affected_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-22STDI069 |
|---------------------------|
| CATALOG_PART_NBR |
| PIC16C55A-04/SS |
| PIC16C55A-04I/SS |
| PIC16C55A-20/SS |
| PIC16C55A-20E/SS |
| PIC16C55A-20I/SS |
| PIC16C55A-40/SS |
| PIC16C55AT-04/SS |
| PIC16C55AT-04I/SS |
| PIC16C55AT-20/SS022 |
| PIC16C55AT-20/SS036 |
| PIC16C55AT-20I/SS |
| PIC16C57C-04/SS |
| PIC16C57C-04I/SS |
| PIC16C57C-20/SS |
| PIC16C57C-20E/SS |
| PIC16C57C-20I/SS |
| PIC16C57C-40/SS |
| PIC16C57CT-04I/SS |
| PIC16C57CT-04I/SS042 |
| PIC16C57CT-20/SS |
| PIC16C62A-04/SS |
| PIC16C62A-20/SS |
| PIC16C62A-20I/SS |
| PIC16C62B-04/SS |
| PIC16C62B-04I/SS |
| PIC16C62B-20/SS |
| PIC16C62B-20I/SS |
| PIC16C62BT-04I/SS |
| PIC16C62BT-20I/SS |
| PIC16C63A-04/SS |
| PIC16C63A-04I/SS |
| PIC16C63A-20/SS |
| PIC16C63A-20E/SS |
| PIC16C63A-20I/SS |
| PIC16C63AT-04/SS |
| PIC16C63AT-20I/SS |
| PIC16C72-04I/SS |
| PIC16C72-10I/SS |
| PIC16C72A-04/SS |
| PIC16C72A-04E/SS |
| PIC16C72A-04I/SS |
| PIC16C72A-20/SS |
| PIC16C72A-20I/SS |
| PIC16C72AT-04/SS |
| PIC16C72AT-20I/SS |

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Affected Catalog Part Numbers (CPN)

| PCN_JAON-22STDI069 |
|---------------------------|
| CATALOG_PART_NBR |
| PIC16C72T-20I/SS |
| PIC16C73B-04/SS |
| PIC16C73B-04I/SS |
| PIC16C73B-20/SS |
| PIC16C73B-20E/SS |
| PIC16C73B-20I/SS |
| PIC16C773/SS |
| PIC16C773-E/SS |
| PIC16C773-I/SS |
| PIC16C773T/SS |
| PIC16C773T-I/SS |
| PIC16F870-E/SS |
| PIC16F870-I/SS |
| PIC16F870T-E/SS |
| PIC16F870T-I/SS |
| PIC16F872-E/SS |
| PIC16F872-I/SS |
| PIC16F872T-I/SS |
| PIC16F872T-I/SS034 |
| PIC16LC55A-04I/SS |
| PIC16LC57C-04/SS |
| PIC16LC57C-04I/SS |
| PIC16LC57CT-04I/SS |
| PIC16LC62A-04/SS |
| PIC16LC62A-04I/SS |
| PIC16LC62B-04/SS |
| PIC16LC62B-04I/SS |
| PIC16LC62BT-04I/SS |
| PIC16LC63A-04/SS |
| PIC16LC63A-04I/SS |
| PIC16LC63AT-04I/SS |
| PIC16LC72-04/SS |
| PIC16LC72A-04I/SS |
| PIC16LC72AT-04I/SS |
| PIC16LC73B-04/SS |
| PIC16LC73B-04I/SS |
| PIC16LC773/SS |
| PIC16LC773-I/SS |
| PIC16LF870-I/SS |
| PIC16LF870T-I/SS |
| PIC16LF872-I/SS |
| PIC16LF872T-I/SS |